

**IN THE CLAIMS**

This listing of claims replaces all prior listings:

1. (Currently Amended) A solid state image pickup device ~~having an image pickup region comprised of~~ comprising:  
a semiconductor region formed on a substrate;  
a plurality of photo-sensors on the semiconductor region; and  
a transfer register for transferring formed in the semiconductor region which transfers  
signal charges accumulated in said photo-sensors[;]; and  
~~said image pickup region formed on the face layer side of a substrate,~~  
wherein  
~~said solid state image pickup device further comprises an impurity region portion~~  
continuously formed in the semiconductor region continuously in a direction orthogonal to  
the transfer direction of said transfer register,  
wherein,  
~~said impurity region portion is provided at a position corresponding to a position~~  
between said photo-sensors adjacent to each other along the transfer direction of said transfer  
register ~~in said substrate~~ in the semiconductor region.
2. (Currently Amended) The solid state image pickup device as set forth in claim 1,  
wherein  
~~said impurity region portion is formed at a position in the semiconductor region~~  
deeper than said transfer register ~~as viewed from the face layer portion side of said substrate.~~
3. (Currently Amended) The solid state image pickup device as set forth in claim 1,  
wherein

a plurality of said impurity region portions are formed in the semiconductor region  
~~depth direction of said substrate.~~

4. (Currently Amended) The solid state image pickup device as set forth in claim 1,  
wherein ~~separately from said impurity region portion,~~ a channel stop region ~~portion~~  
comprised of an impurity region is formed, separately from said impurity region, between  
said photo-sensors adjacent to each other along the transfer direction of said transfer register  
and in the vicinity of the surface of said ~~substrate~~ semiconductor region.

5. (Currently Amended) The solid state image pickup device as set forth in claim 1,  
further comprising an overflow barrier formed ~~in-between the semiconductor layer and said~~  
~~substrate on the deep layer portion side relative to said photo-sensors and said transfer~~  
~~register,~~

wherein,

said overflow barrier is in a projected and recessed shape at an interface thereof in the  
~~depth~~ direction of said substrate, and

a projected portion of said projected and recessed shape is disposed at a position  
corresponding to a position between said photo-sensors.

6. (Currently Amended) The solid state image pickup device as set forth in claim 1,  
wherein in addition to said impurity region portion, a first barrier region portion comprised of  
an impurity region is provided at a position between said photo-sensors adjacent to each other  
in the transfer direction of said transfer register and shallower relative to said impurity region  
portion as viewed from the semiconductor region ~~face layer portion side of said substrate.~~

7. (Original) The solid state image pickup device as set forth in claim 1, further comprising a second barrier layer comprised of an impurity region portion formed along said transfer register.

8. (Currently Amended) The solid state image pickup device as set forth in claim 7, further comprising an overflow barrier formed ~~in-between~~ said semiconductor region and the substrate on the deep layer portion side relative to said photo-sensors and said transfer register, wherein said overflow barrier is in a projected and recessed shape at an interface of said photo-sensors and said transfer register ~~side in the depth direction of said substrate~~, and a projected portion of said projected and recessed shape is disposed at a position corresponding to a position between said photo-sensors.

9. (Original) The solid state image pickup device as set forth in claim 5, wherein said impurity region portion is higher than said overflow barrier in impurity concentration.

10. (Original) The solid state image pickup device as set forth in claim 8, wherein said impurity region portion is higher than said overflow barrier in impurity concentration.

11. (Currently Amended) The solid state image pickup device as set forth in claim 7, wherein said impurity region portion and said second barrier region portion are located at the same depth ~~as viewed from the face layer portion side of said substrate~~.

12. (Withdrawn) A solid state image pickup device having an image pickup region comprised of a plurality of photo-sensors and a transfer register for transferring signal charges accumulated in said photo-sensors, said image pickup region formed on the face layer portion side of a substrate, wherein said solid image pickup device further comprises

an impurity region portion formed in said substrate continuously with a position between said photo-sensors adjacent to each other in the transfer direction of said transfer register.

13. (Withdrawn) The solid state image pickup device as set forth in claim 12, wherein said impurity region portion is formed at a position deeper than said transfer register as viewed from the face layer portion side of said substrate.

14. (Withdrawn) The solid state image pickup device as set forth in claim 12, further comprising a second barrier region portion comprised of an impurity region formed along said transfer register.

15. (Withdrawn) A method of manufacturing a solid state image pickup device, comprising the steps of:

forming on the face layer portion side of a substrate a plurality of photo-sensors and a transfer register for transferring signal charges accumulated in said photo-sensors; and forming an impurity region portion continuously in said substrate at a position between said photo-sensors adjacent to each other along the transfer direction of said transfer register.

16. (Withdrawn) The method of manufacturing a solid state image pickup device as set forth in claim 15, wherein said impurity region portion is formed at a position deeper than said transfer register as viewed from the face layer portion side of said substrate.

17. (Withdrawn) The method of manufacturing a solid state image pickup device as set forth in claim 15, wherein a plurality of said impurity region portions are formed in the depth direction of said substrate.

18. (Withdrawn) The method of manufacturing a solid state image pickup device as set forth in claim 15, further comprising the step of forming an overflow barrier in said substrate on the deep layer portion side relative to said photo-sensors and said transfer register, wherein said overflow barrier is in a projected and recessed shape at an interface thereof in the depth direction of said substrate, and a projected portion of said projected and recessed shape is disposed at a position corresponding to a position between said photo-sensors.

19. (Withdrawn) The method of manufacturing a solid state image pickup device as set forth in claim 15, further comprising the step of forming a first barrier region portion comprised of an impurity region at a position between said photo-sensors adjacent to each other along the transfer direction of said transfer register and deeper than said impurity region portion as viewed from the face layer portion side of said substrate.

20. (Withdrawn) The method of manufacturing a solid state image pickup device as set forth in claim 15, further comprising the step of forming a second barrier region portion comprised of an impurity region along said transfer region.